

DATASHEET

1206 Package Chip Infrared LED With Inner Lens HIR11-21C/L11/TR8



Features

- High reliability
- Small double-end package
- Peak wavelength λ p=850nm
- Package in 8mm tape on 7" diameter reel
- Low forward voltage
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH

Descriptions

HIR11-21C/L11/TR8 is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic With flat top view lens.

The device is spectrally matched with silicon photodiode and phototransistor.

Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Smoke detector
- Infrared applied system

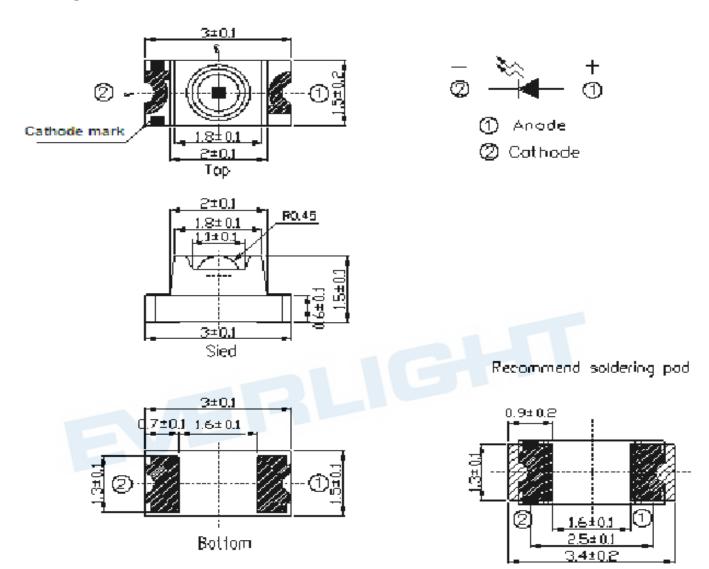
Device Selection Guide

Part Category	Chip Material	Resin Color	
HIR	GaAlAs	Water Clear	

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Package Dimensions



- Notes: 1.All dimensions are in millimeters
 - 2. Tolerances unless dimensions ±0.1 mm
 - 3. Suggested pad dimension is just for reference only Please modify the pad dimension based on individual need



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_{F}	65	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-25 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Soldering Temperature *1	T_{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below)	P_d	130	mW
25°C Free Air Temperature			

Notes: *1. Soldering time \leq 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

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Parameter	Symbol	Condition	Min.	Тур.	Max.	Units		
Radiant Intensity	Ie	I _F =20mA	1.0	2.0	17	mW /sr		
Peak Wavelength	λp	I _F =20mA		850		nm		
Spectral Bandwidth	Δλ	I _F =50mA		45		nm		
Forward Voltage	V_{F}	I _F =20mA		1.45	1.65	V		
Reverse Current	I_R	V _R =5V			10	μΑ		
View Angle	2 0 1/2	I _F =20mA		80		deg		

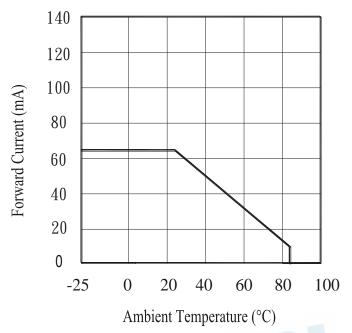


Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

Fig.2 Spectral Distribution



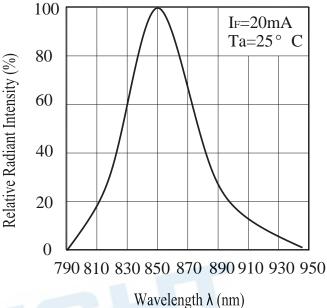
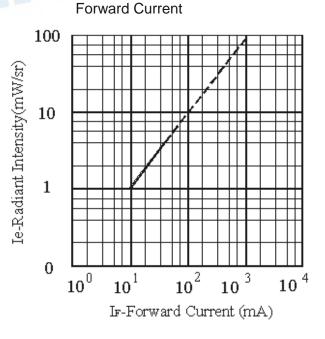


Fig.3 Forward Current

vs. Forward Voltage 104 $tp{-}100\,\mu <$ Forward Current IF(mA) tp T-0.01 10³ 102 101 0 2 3 5 б 7 8 -) 4 Forward Voltage (V)

Fig.4 Relative Intensity vs.

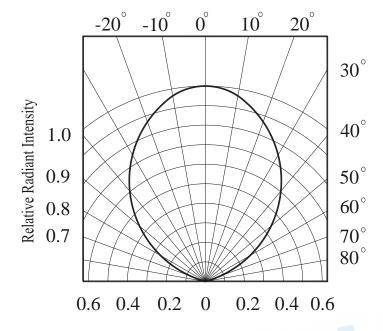




Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs.

Angular Displacement





Precautions For Use

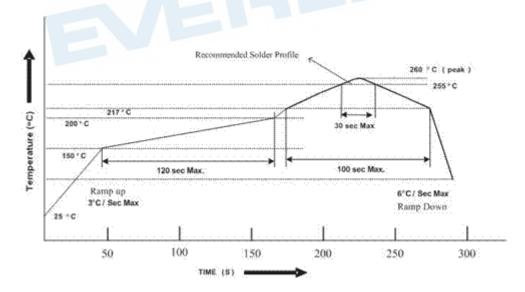
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90% RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5°C for 24 hours.
- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

Data Sheet

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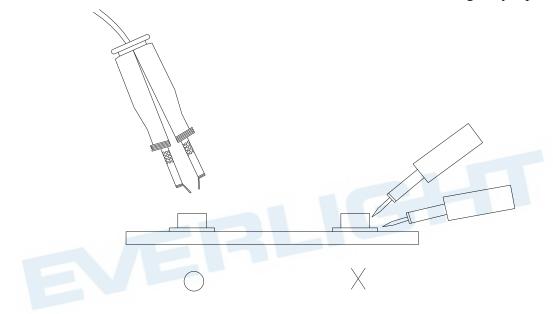


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

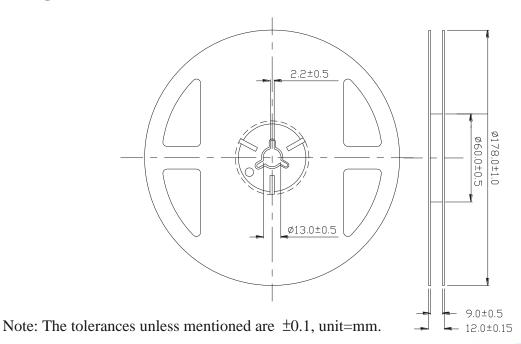
5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

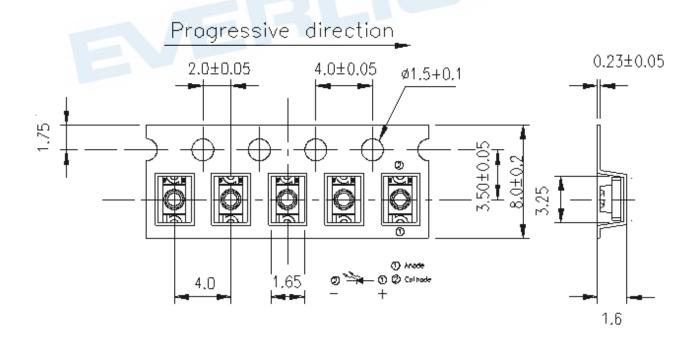




Package Dimensions



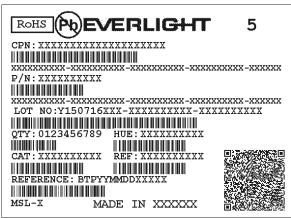
Carrier Taping Dimensions: Loaded Quantity Per Reel 3000PCS/Reel



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number LOT No: Lot Number

QTY: Packing Quantity HUE: Peak Wavelength

CAT: Ranks REF: Reference MSL-X: MSL Level

Made In: Manufacture place

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- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from

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- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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